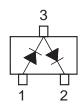
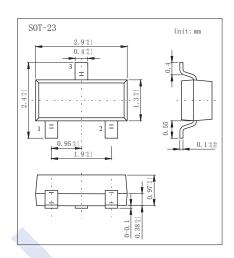
SMD Type Diodes

Switching Diodes 1KS3004

■ Features

- Fast Switching Speed
- For General Purpose Switching Applications.
- High Conductance





■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit			
Repetitive Peak Reverse Voltage	VRRM	100	V			
Continuous Reverse Voltage	VR	V				
Forward Current (Double Diode Loaded)	IF	150				
Forward Current (Single Diode Loaded)	1 1 1 1	250	mA			
Repetitive Peak Forward Current	IFRM	450				
t=1s	IFSM	1				
Non-repetitive Peak Forward Surge Current t=1ms		2	Α			
t=1us		4				
Power Dissipation	Pd	350	mW			
Junction Temperature	TJ	150	°C			
Storage Temperature range	Tstg	-65 to 150	C			

■ Electrical Characteristics Ta = 25°C

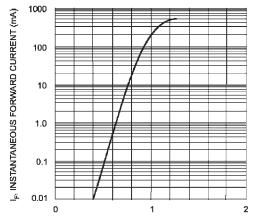
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Reverse breakdown voltage	VR	IR= 100 uA	100			
Forward voltage		IF= 1 mA			0.715	
	VF	IF= 10 mA			0.855	V
		IF= 50 mA			1	
		IF= 150 mA			1.25	
	lr	VR= 25 V			30	nA
Reverse voltage leakage current		VR= 75 V			1	
		VR= 25 V , TJ=150℃			30	uA
		VR= 75 V , TJ=150°C			50	
Junction capacitance	Cj	VR= 0 V, f= 1 MHz			1.5	pF
Reverse recovery time	trr	IF=IR=10mA,IR=1mA, RL=100Ω			4	ns

■ Marking

SMD Type Diodes

Switching Diodes 1KS3004

■ Typical Characterisitics



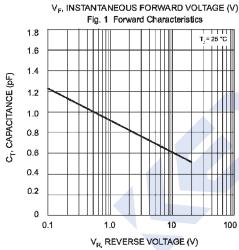
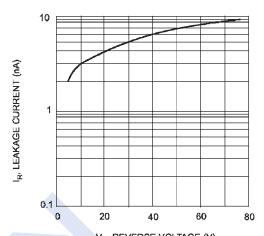


Fig. 3 Typical Total Capacitance vs Reverse Voltage



V_R, REVERSE VOLTAGE (V)
Fig. 2 Typical Leakage Current vs Reverse Voltage



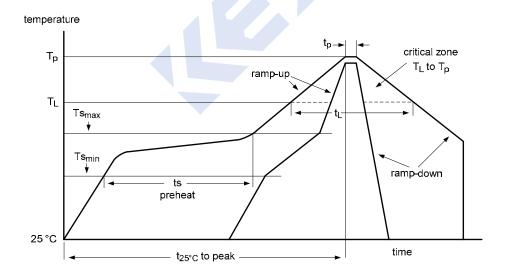
SMD Recommended Reflow Soldering Profile

Recommended Reflow Soldering Profile

The below temperature profile for moisture sensitivity characterization is based on the IPC/JEDEC joint industry standard: J-STD-020D-01.

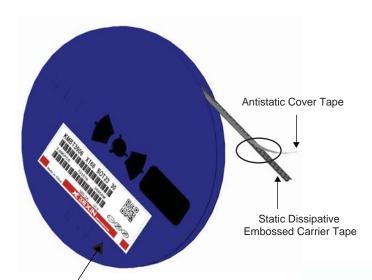
Profile Feature	SnPb eutectic assembly	Pb-free assembly		
Average ramp-up rate (T _{smax} to T _p)	3 °C/s maximum	3 °C/s maximum		
Preheat				
Temperature minimum (T _{smin})	100 °C	150 °C		
Temperature maximum (T _{smax})	150 °C	200 °C		
Time $(t_{smin} \text{ to } t_{smax})$	60 s to 120 s	60 s to 180 s		
Time maintained above				
Temperature (T _L)	183 °C	217 °C		
Time (t _L)	60 s to 150 s	60 s to 150 s		
Peak/classification temperature (Tp)	235 °C	260 °C		
Number of allowed reflow cycles	3	3		
Time within 5 °C of actual peak temperature (tp)	10 s to 30 s	20 s to 40 s		
Ramp-down rate	6 °C/s maximum	6 °C/s maximum		
Time 25 °C to peak temperature	6 minutes maximum	8 minutes maximum		

Reflow Soldering Profile



SOT-23 Tape and Reel Data

1. SOT-23 Packing Configuration:



Packaging Description

SOT-23 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, Adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 17.7cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated). This and some other options are further described in the Packaging Information table. These full reels are individually barcode labeled and placed inside a standard intermediate box made of recyclable corrugated brown paper. One box contains ten reels maximum. And these boxes are placed inside a barcode labeled shipping box which comes in different sizes depending on the number of parts shipped.

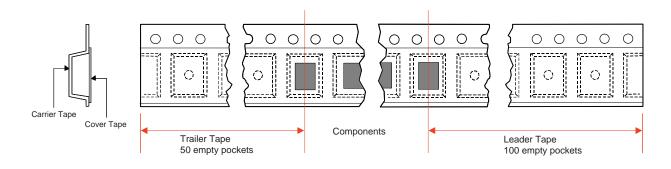


Label

SOT-23 Unit Orientation

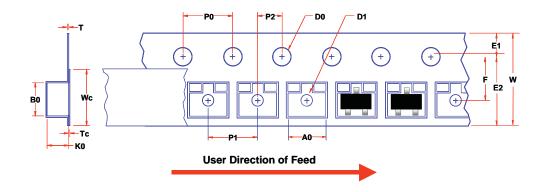


2. SOT-23 Tape Leader and Trailer Configuration:



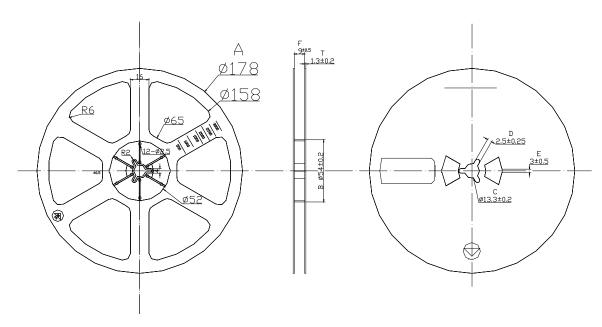
SOT-23 Tape and Reel Data

3. SOT-23 Embossed Carrier Tape Configuration:



Dimension are in millimeter															
Pkg type	A0	В0	w	D0	D1	E1	E2	F	P2	P1	P0	K0	т	Wc	Тс
SOT-23	3.20 +/-0.10	2.85 +/-0.10	8.0 +/-0.3	1.50 +0.10	1.0 +/-0.1	1.75 +/-0.10	6.25 min	3.50 +/-0.05	2.0 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.22 +/-0.10	0.2 +/-0.02	5.4 +/-0.1	0.05 +/-0.02

4. SOT-23 Reel Configuration:



NOTES: ALL DIMENSION ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED